

TF1210A2X Series

COMMON MODE FILTER

TOP-EMC

Generals

- This specification covers the engineering requirements for the TF1210A2X series (Common Mode Filter)

Features

- Miniature footprint : 1.25 × 1.00 × 0.6 mm
- Multilayer LTCC (Low Temperature Cofired Ceramic) Technology
- Special 3D layout design to minimize phase shifting
- High Attenuation for common mode noise
- Reflow solderable SMD Devices
- Compliant with AEC-Q200



Applications

- Suppress the emission noise for vehicle multimedia interfaces (MOST, HDMI, IDB-1394, etc.).

Explanation of Part Numbers

T F 1210A 2X 900 M T
① ② ③ ④ ⑤ ⑥ ⑦

- ① Company Name : TOP-EMC
- ② Product Function : Common Mode Filter
- ③ Dimensions : 1.25mm(L) × 1.00mm(W)
- ④ Number of lines : 2X = 2 lines
- ⑤ Common Mode Impedance (at 100MHz) : 900= 90Ω
- ⑥ Tolerance of common mode impedance : M=±25%
- ⑦ Packing : Tape & Reel

Electrical Characteristics

Part Number	Common Mode Impedance (at 100MHz, Under Standard Testing Condition)	Rated Voltage	Withstanding Voltage	Rated Current	Max. DC Resistance	Insulation Resistance
TF1210A2X650MT	$65\Omega \pm 25\%$	10V(DC)	25V(DC)	300mA	0.6 Ω	200M Ω
TF1210A2X900MT	$90\Omega \pm 25\%$					
TF1210A2X121MT	$120\Omega \pm 25\%$					

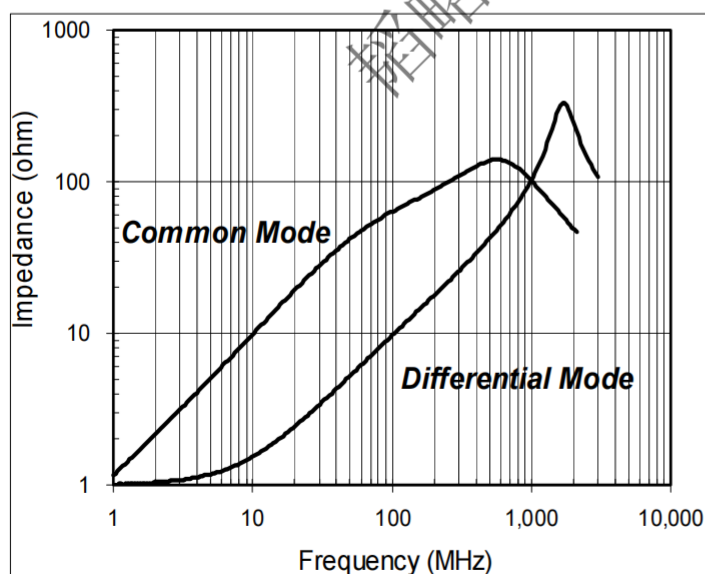
Note

Operating Temperature : -40°C ~ +125°C

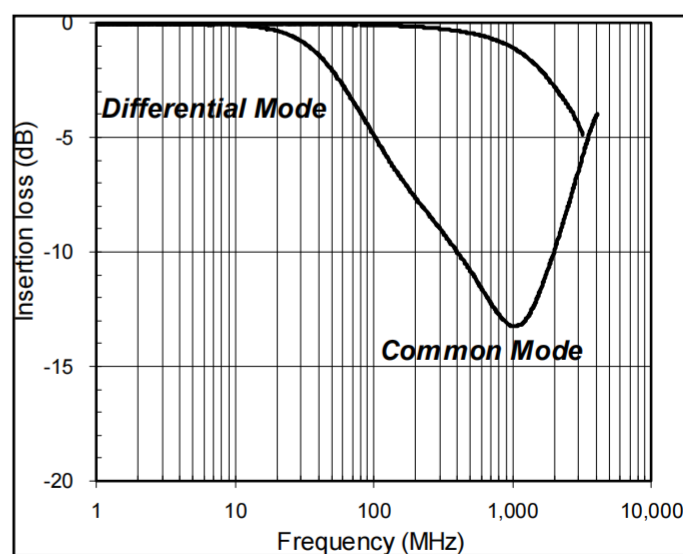
Typical Characteristics

TF1210A2X650MT

IMPEDANCE vs. FREQUENCY CHARACTERISTICS



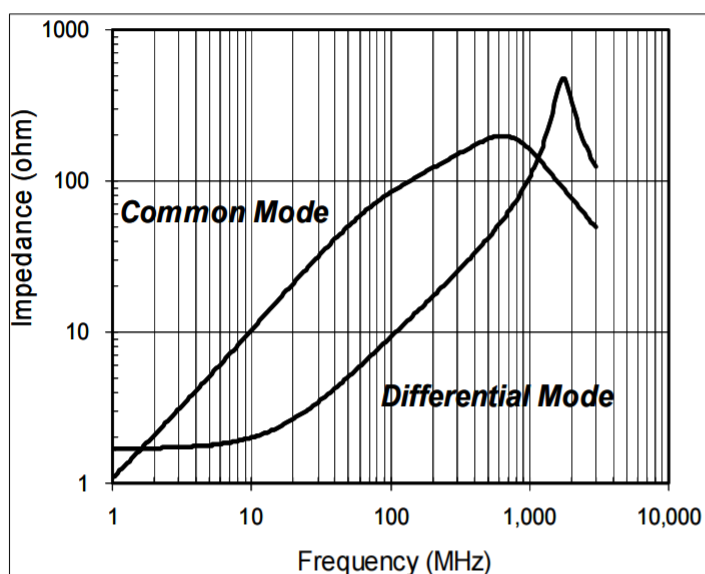
INSERTION LOSS vs. FREQUENCY CHARACTERISTICS



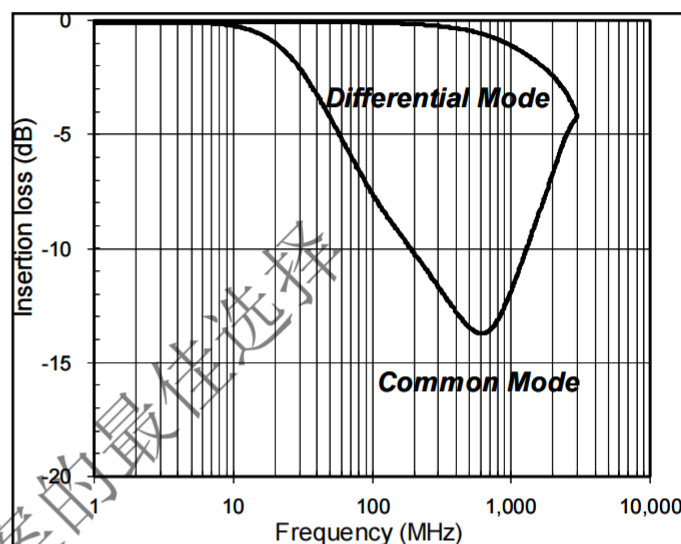
Typical Characteristics

TF1210A2X900MT

IMPEDANCE vs. FREQUENCY CHARACTERISTICS

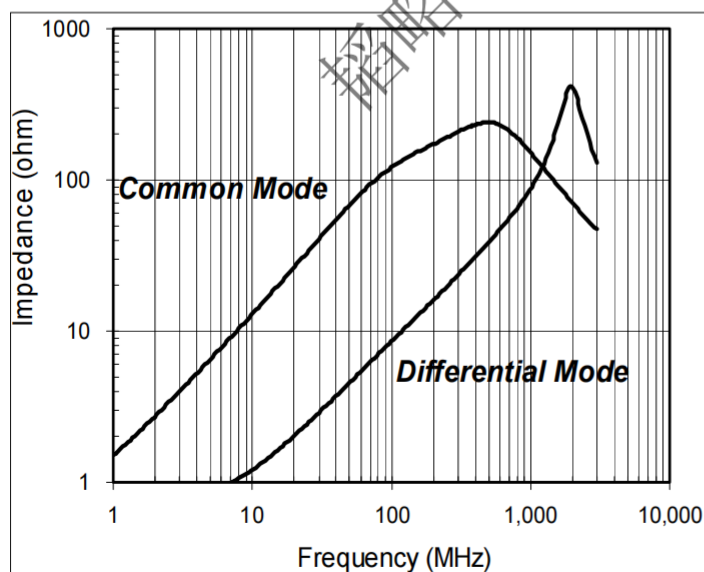


INSERTION LOSS vs. FREQUENCY CHARACTERISTICS

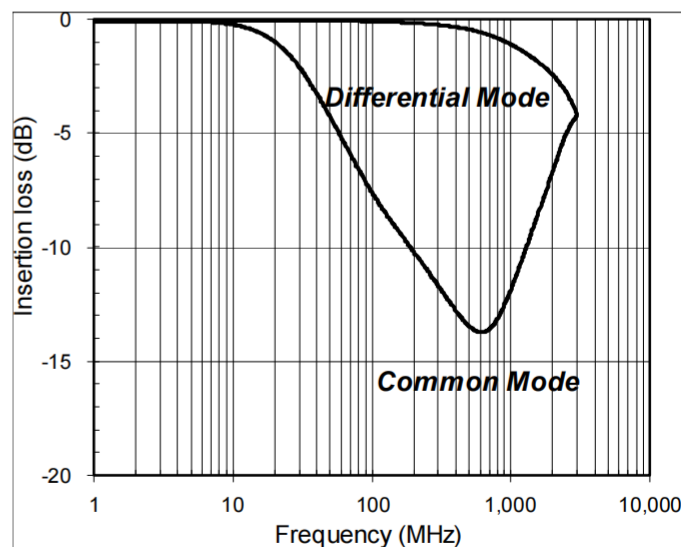


TF1210A2X121MT

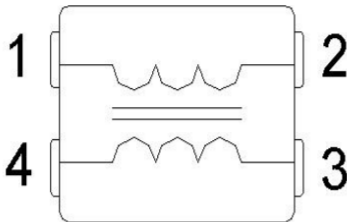
IMPEDANCE vs. FREQUENCY CHARACTERISTICS



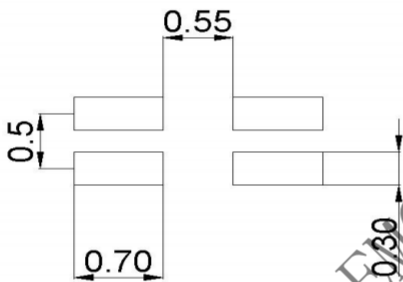
INSERTION LOSS vs. FREQUENCY CHARACTERISTICS



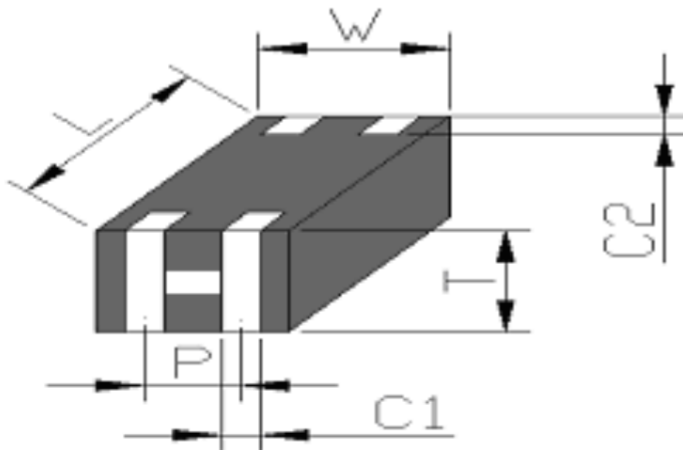
Circuit Configuration and



Layout Pad

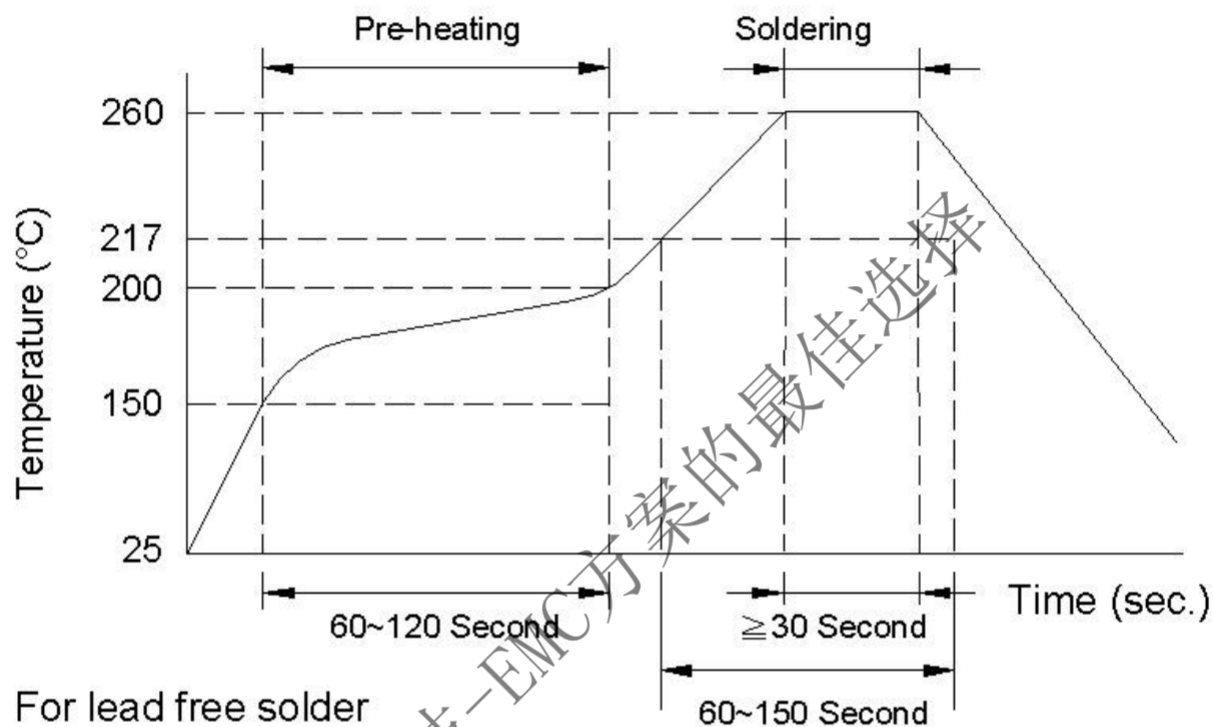


Appearance and Dimension



TYPE	1210
L	1.25±0.10
W	1.00±0.10
T	0.60±0.10
P	0.50±0.10
C1	0.30±0.10
C2	0.20±0.15
Unit: mm	

Recommended Soldering Conditions



NOTE

The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres the terminals will oxidize and solderability will be affected.

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